



YOLE DÉVELOPPEMENT

PRESS RELEASE

Advanced Packaging Activity at Yole Développement

Jean-Marc Yannou joins Yole Développement as Project Manager for Advanced Packaging, Wafer-Level Packaging and 3D System Integration

Sept. 29, 2009 – Yole Développement has appointed Jean-Marc Yannou as Project Manager for Advanced Packaging, WLP and 3D System integration. This recruitment confirms Yole Développement's strategy to increase its activity in the Advanced Packaging industry. Yole Développement has been working on this sector for several years now and proposes consulting services as well as different market & technological studies.

Jean-Marc Yannou joins Yole Développement to reinforce the advanced packaging team. Thanks to his deep industry experience and knowledge, Jean-Marc will help Yole Développement meet the rising demand from the semiconductor packaging industry for technology updates, market forecasts, supply chain mappings and marketing analyses. Jean-Marc will also help Yole Développement to further extend its reach to hardware system integrators of electronic systems.

During the past 5 years, Jean-Marc served Philips (then NXP Semiconductors) as an Innovation Manager for System-in-Package technologies. Jean-Marc built the technology roadmap of the company covering the scope of advanced packaging for SiP integration and Integrated Passive Devices. Jean-Marc also acted as a business developer for these technologies. In his role to promote new developments, Jean-Marc initiated large size projects and tied partnerships. He made up to 20 publications and he chaired 4 conference sessions. He is the co-author of 6 international patents in the fields of packaging and test.

Previously, Jean-Marc worked as a Test and Product engineer at Texas Instruments in Dallas, TX, USA and in France, and as a Design for Test Engineer at Philips.

Since he joined the company, Jean-Marc, together with Yole's colleagues, issued a first report on thin-film Integrated Passive Devices, named "IPD 2009". *"This is the first report ever dedicated to this promising market, with worldwide sales expected to reach one billion dollars by 2013, and an expected CAGR of 16% from 2008 to 2015" Développement", explained Jean-Marc Yannou, Project Manager at Yole Développement*

About Yole Développement in the Advanced Packaging industry

From technologies to market, we help our clients to develop their business in the Advanced Packaging industry. Our commitment is to facilitate market access for innovative technologies, equipment and materials.

45 rue Sainte Geneviève, F-69006 Lyon
Tél. : +33 472 83 01 80 – Fax : +33 472 83 01 83 – Web : www.yole.fr
SA au capital de 115 736.50 € – Siret : 421 162 785 00016, APE 741G



Materials and equipment: Yole's expertise

- Materials or equipment for encapsulation, contact deposition, testing... those are typical subjects we study on specific request from our customers. Yole investigates to understand the main trends and issues and provide analysis for strategic action.
- Yole can assist you with risk evaluation and supplier evaluation.

Tracking around 1000 Advanced Packaging companies on a daily basis

- Yole Développement works worldwide with the key industrial companies, R&D institutes and investors in order to help them to understand the markets and technology trends. We take into account the complete value chain in our analysis, from materials and equipment business to device and system manufacturers and final users.
- Yole is working with its customers at every stages of the development, from R&D to industrial development, from initial ideas to market launch of finished products.

Contacts

Yole Développement

45 Rue Ste Geneviève, 69006 Lyon, France

Tel : +33 (0) 472 83 01 80

Fax : +33 (0) 472 83 01 83

www.yole.fr

About Yole Développement, please contact Jean Christophe Eloy, CEO, eloy@yole.fr

About this report and Advanced Packaging activity, Jérôme Baron (baron@yole.fr) and Jean-Marc Yannou (yannou@yole.fr)